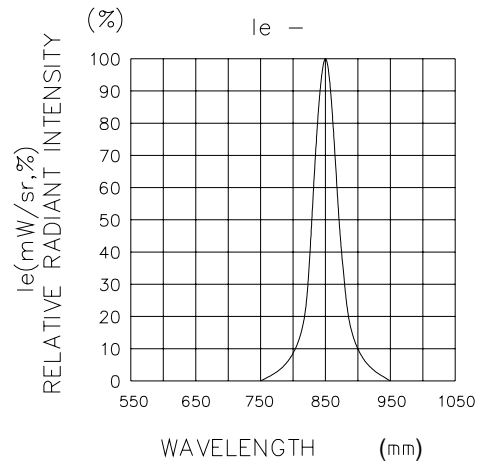
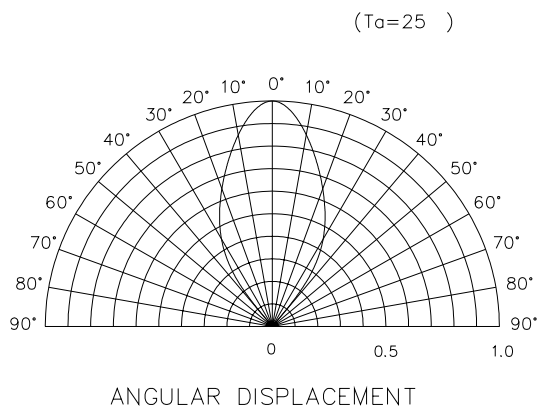
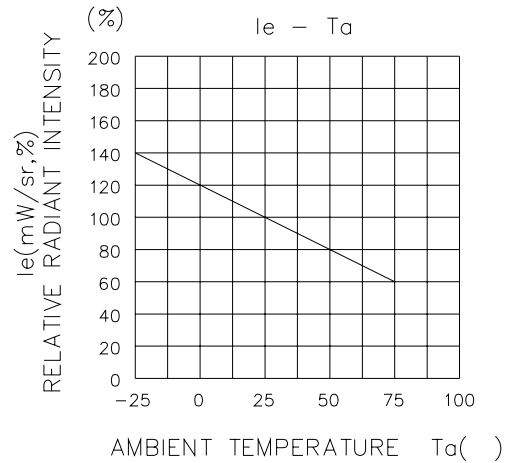
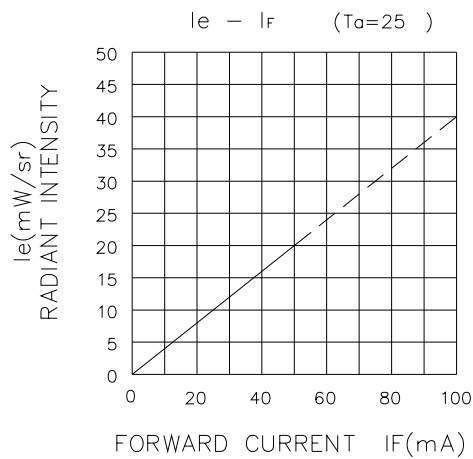
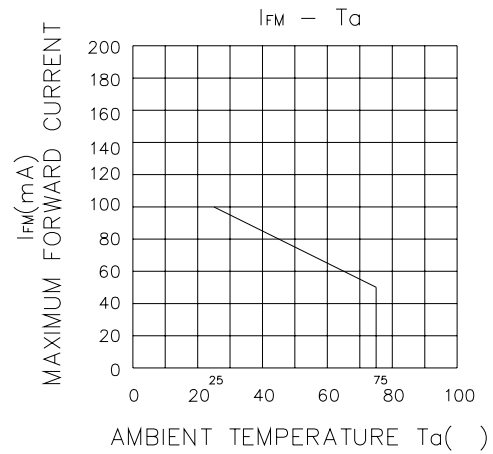
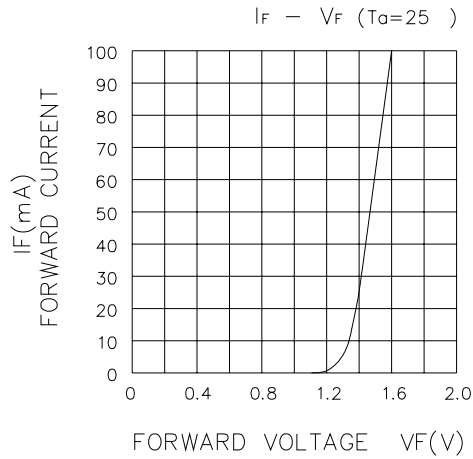




RODAN(TAIWAN)LTD.

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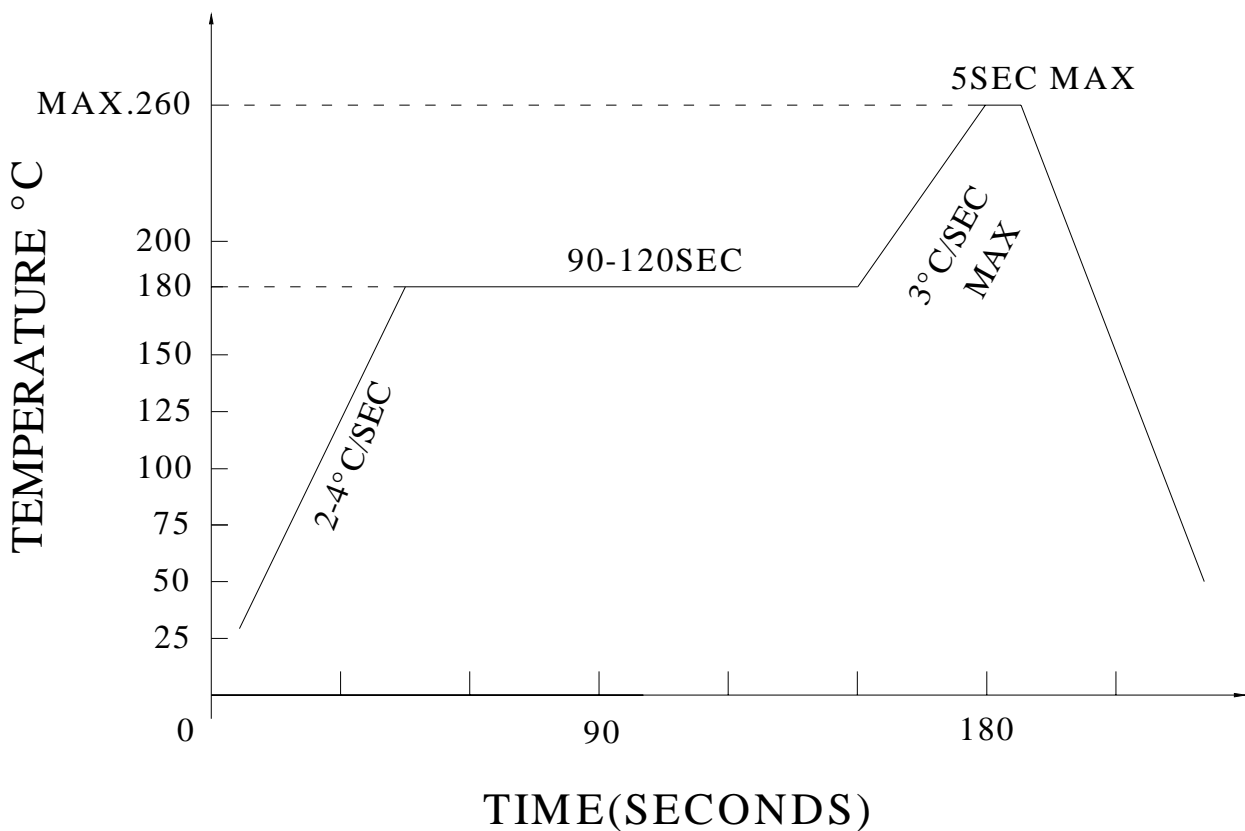


Lamp Condition

In the automatic mounting of LAMP LED to the L/F, any bending, expanding, and pulling forces against the LAMP LED should be minimized to prevent the electrical failures or mechanical damaged.

Reflow Soldering and Temperature Profile

The LAMP LED is designed for the reflow soldering process. Too high temperature or too large temperature gradient may cause the electrical and optical failures.





Reliability Test Items

CONDITIONS :

The reliability of products shall be satisfied with items listed below.

NO.	Item	Condition	Time/Cycle	Number of Damaged
1	Soldering Heat Test	260	5 sec	0/60
2	Thermal Shock	0 (15sec) ~100 (15sec)	20 cycle	0/60
3	High Temp. Storage	100	1000 Hrs	0/60
4	Low Temp. Storage	-25	1000 Hrs	0/60
5	Operation Temperature Cycle Test	-25 ~75	100 Cycles , 200Hrs	0/60
6	High Temp. High Humidity Test	60 , 90% RH	1000Hrs	0/60
7	Operation Life Test	Room Temp.50mA	1000Hrs	0/60